



---

DATE: July 27, 2026

PCN #: 2837

PCN Title: Qualification of Internal "Diodes Technology (Cheng Du) Company Limited" (CAT) as Additional Assembly & Test (A/T) Site with Standardization of Assembly Bill of Materials for Select Discrete Products

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of notification by contacting your local Diodes sales representative. If you require samples for evaluation purposes, please submit a corresponding request within 30 days as well. Otherwise, samples may not be built prior to the implementation of the announced change(s).

The change(s) announced in this PCN will not be implemented prior to the target implementation date, i.e. 90 days from the stated notification date, unless Diodes receives written customer approval before that date.

Previously agreed upon customer specific product and/or process change requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



## PRODUCT CHANGE NOTICE

PCN-2837-REV1

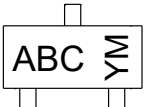
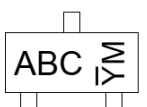
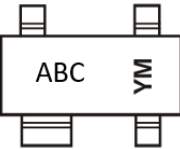
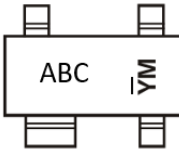
| Notification Date:                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           | Implementation Date:                                                                                                                                                                    | Product Family:        | Change Type:                                                    | PCN #: |
|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|-----------------------------------------------------------------|--------|
| July 27, 2026                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                | October 26, 2026                                                                                                                                                                        | Discrete Semiconductor | Additional Assembly & Test Site /<br>Assembly Bill of Materials | 2837   |
| TITLE                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                        |                                                                                                                                                                                         |                        |                                                                 |        |
| Qualification of Internal "Diodes Technology (Cheng Du) Company Limited" (CAT) as Additional Assembly & Test (A/T) Site with<br>Standardization of Assembly Bill of Materials for Select Discrete Products                                                                                                                                                                                                                                                                                                                   |                                                                                                                                                                                         |                        |                                                                 |        |
| DESCRIPTION OF CHANGE                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                        |                                                                                                                                                                                         |                        |                                                                 |        |
| This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified internal "Diodes Technology (Cheng Du) Company Limited" (CAT) located in Chengdu, China as additional Assembly and Test (A/T) site for select discrete products listed below. This A/T site change also includes standardization of assembly bill of materials, i.e. mold compound, lead frame type, die attach material and type, bond wire composition and diameter, and date code marking changes at CAT. |                                                                                                                                                                                         |                        |                                                                 |        |
| Full electrical characterization and high reliability testing have been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet.                                                                                                                                                                                                                                                                                                         |                                                                                                                                                                                         |                        |                                                                 |        |
| There will be no change to Fit or Function of products affected.                                                                                                                                                                                                                                                                                                                                                                                                                                                             |                                                                                                                                                                                         |                        |                                                                 |        |
| IMPACT                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                       |                                                                                                                                                                                         |                        |                                                                 |        |
| Continuity of Supply. No change in datasheet electrical parameters and product performance.                                                                                                                                                                                                                                                                                                                                                                                                                                  |                                                                                                                                                                                         |                        |                                                                 |        |
| PRODUCTS AFFECTED                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                            |                                                                                                                                                                                         |                        |                                                                 |        |
| Please see the attached part list and part marking change in the following tables:<br>Table 1 – Affected part list to qualify CAT as additional A/T site with standardization of assembly bill of materials at CAT<br>Table 2 – Part Marking Format                                                                                                                                                                                                                                                                          |                                                                                                                                                                                         |                        |                                                                 |        |
| WEB LINKS                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    |                                                                                                                                                                                         |                        |                                                                 |        |
| Manufacturer’s Notice:                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                       | <a href="https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/">https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/</a> |                        |                                                                 |        |
| For More Information Contact:                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                | <a href="https://www.diodes.com/about/contact-us/contact-sales/">https://www.diodes.com/about/contact-us/contact-sales/</a>                                                             |                        |                                                                 |        |
| Data Sheet:                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                  | <a href="https://www.diodes.com/catalog/">https://www.diodes.com/catalog/</a>                                                                                                           |                        |                                                                 |        |
| DISCLAIMER                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                   |                                                                                                                                                                                         |                        |                                                                 |        |
| Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days from the notification date of this PCN, all changes described in this announcement are considered approved.                                                                                                                                                                                                                                                                                                                         |                                                                                                                                                                                         |                        |                                                                 |        |

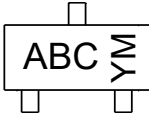
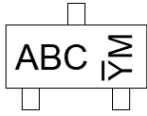
**Table 1 - Affected part list to qualify CAT as additional A/T site with standardization of assembly bill of materials at CAT**

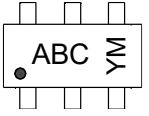
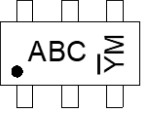
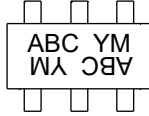
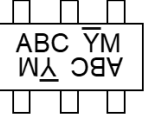
|               |               |                |                |                 |                |
|---------------|---------------|----------------|----------------|-----------------|----------------|
| BZX84B10-7-F  | BZX84B33-7-F  | BZX84B7V5-7-F  | D1213A-04V-7   | L50L5V0CB2*     | MMSZ5255BS-7-F |
| BZX84B11-7-F  | BZX84B36-7-F  | BZX84B8V2-7-F  | D12V0M1U2T-7   | MMBZ15VALA-7    | MMSZ5256B-13-F |
| BZX84B12-7-F  | BZX84B39-7-F  | BZX84B9V1-7-F  | D24V0S1U2T-7   | MMBZ5255BW-7-F  | MMSZ5256B-7-F  |
| BZX84B13-7-F  | BZX84B3V0-7-F | BZX84C30S-7-F  | D3V3L1B2T-7    | MMBZ5256BS-7-F  | MMSZ5256BS-7-F |
| BZX84B15-7-F  | BZX84B3V3-7-F | BZX84C30W-7-F  | D3V3L1B2WS-7   | MMBZ5256BW-7-F  | MMSZ5257B-7-F  |
| BZX84B16-7-F  | BZX84B3V6-7-F | BZX84C36S-7-F  | D5V0F1B2WS-7*  | MMBZ5258BS-7-F  | MMSZ5257BS-7-F |
| BZX84B18-7-F  | BZX84B3V9-7-F | BZX84C39S-7-F  | D5V0FA1B2WS-7* | MMBZ5258BW-7-F  | MMSZ5258B-7-F  |
| BZX84B20-7-F  | BZX84B4V3-7-F | D1213A-01SO-7  | DDZ28-7        | MMBZ5259BS-7-F  | MMSZ5258BS-7-F |
| BZX84B22-7-F  | BZX84B4V7-7-F | D1213A-01W-7   | DDZ30DS-7      | MMBZ5259BTS-7-F | MMSZ5259B-7-F  |
| BZX84B24-7-F  | BZX84B5V1-7-F | D1213A-01WS-7  | DDZ34-7        | MMBZ5V6ALA-7    | MMSZ5259BS-7-F |
| BZX84B27-7-F  | BZX84B6V2-7-F | D1213A-02SOL-7 | L03ESDL5V0CA2  | MMBZ6V8ALA-7    | MMSZ5263B-7-F  |
| BZX84B2V7-7-F | BZX84B6V8-7-F | D1213A-02SR-7  | L25L5V0CB2*    | MMSZ5255B-7-F   | T5V0S5-7       |
| BZX84B30-7-F  |               |                |                |                 |                |

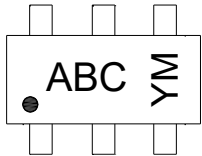
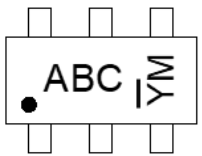
Note: "\*" Change bond wire from Au to Cu. Otherwise, change bond wire from Au to PdCu for the remaining devices.

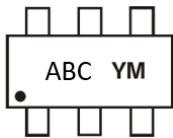
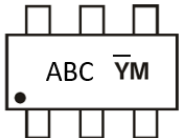
**Table 2: Part Marking Format –**

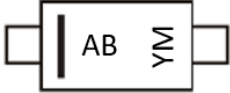
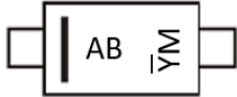
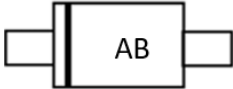
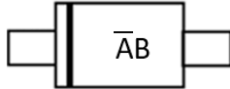
|        | CURRENT                                                                                                        | NEW                                                                                                              |
|--------|----------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------|
|        | SAT<br>(Diodes Internal A/T Site - Shanghai, China)                                                            | CAT<br>(Diodes Internal A/T Site - Chengdu, China)                                                               |
|        | No Bar "-" and YM Date code format                                                                             | Add bar "-" above Y (Year) of Date Code                                                                          |
| SOT23  | Marking Format Example:<br> | Marking Format Example:<br> |
| SOT143 | Marking Format Example:<br> | Marking Format Example:<br> |

| SOT323 | SAT<br>(Diodes Internal A/T Site - Shanghai, China)                                                          | CAT<br>(Diodes Internal A/T Site - Chengdu, China)                                                             |
|--------|--------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------|
|        | No Bar "-" and YM Date code format                                                                           | Add bar "-" above Y (Year) of Date Code                                                                        |
|        | Marking Format Example:<br> | Marking Format Example:<br> |

| SOT363 | SAT<br>(Diodes Internal A/T Site - Shanghai, China)                                                          | CAT<br>(Diodes Internal A/T Site - Chengdu, China)                                                             |
|--------|--------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------|
|        | No Bar "-" and YM Date code format                                                                           | Add bar "-" above Y (Year) of Date Code                                                                        |
|        | Marking Format Example:<br> | Marking Format Example:<br> |
|        |                            |                            |

| TSOT23-6 | SAT<br>(Diodes Internal A/T Site - Shanghai, China)                                                            | CAT<br>(Diodes Internal A/T Site - Chengdu, China)                                                               |
|----------|----------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------|
|          | No Bar "-" and YM Date code format                                                                             | Add bar "-" above Y (Year) of Date Code                                                                          |
|          | Marking Format Example:<br> | Marking Format Example:<br> |

| SOT563 | SAT<br>(Diodes Internal A/T Site - Shanghai, China)                                                            | CAT<br>(Diodes Internal A/T Site - Chengdu, China)                                                               |
|--------|----------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------|
|        | No Bar "-" and YM Date code format                                                                             | Add bar "-" above Y (Year) of Date Code                                                                          |
|        | Marking Format Example:<br> | Marking Format Example:<br> |

|               |                                                                                                               |                                                                                                                 |
|---------------|---------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------|
| <b>SOD123</b> | <b>SAT</b><br>(Diodes Internal A/T Site - Shanghai, China)                                                    | <b>CAT</b><br>(Diodes Internal A/T Site - Chengdu, China)                                                       |
|               | No Bar "-" and YM Date code format                                                                            | Add bar "-" above Y (Year) of Date Code                                                                         |
|               | Marking Format Example:<br>  | Marking Format Example:<br>  |
| <b>SOD323</b> | <b>SAT</b><br>(Diodes Internal A/T Site - Shanghai, China)                                                    | <b>CAT</b><br>(Diodes Internal A/T Site - Chengdu, China)                                                       |
|               | No Bar "-" and No Date Code                                                                                   | Add bar "-" above the 1st letter                                                                                |
|               | Marking Format Example:<br>  | Marking Format Example:<br>  |
| <b>SOD523</b> | <b>SAT</b><br>(Diodes Internal A/T Site - Shanghai, China)                                                    | <b>CAT</b><br>(Diodes Internal A/T Site - Chengdu, China)                                                       |
|               | No Bar "-" and No Date Code                                                                                   | Add bar "-" above the 1st letter                                                                                |
|               | Marking Format Example:<br> | Marking Format Example:<br> |



|                    |                    |
|--------------------|--------------------|
| Summary:           |                    |
| Submitted By/Date: | Yang Chen 07/14/26 |
| Approved By/Date:  | CW Lin, 7/15/2026  |



## Certificate of Design, Construction & Qualification

[illegible]



|  |  | Product Assembly |  | Part Number Package Type                            |  |                          |  | Qual Device 1                                    |  | Qual Device 2                         |  | Source device 1                      |  | Source device 2                    |  | Source device 3                           |  | Source device 4                          |  | Source device 5                          |  | Source device 6                         |  |
|--|--|------------------|--|-----------------------------------------------------|--|--------------------------|--|--------------------------------------------------|--|---------------------------------------|--|--------------------------------------|--|------------------------------------|--|-------------------------------------------|--|------------------------------------------|--|------------------------------------------|--|-----------------------------------------|--|
|  |  | Wafer            |  | Die Name(s)                                         |  | Die Process / Technology |  | MM5Z5231BQ-7-F-73<br>SOD-123<br>N3051-QE30742023 |  | DDZ6V2BQ-13<br>SOD-123<br>240GB-12005 |  | AZ23C3V9Q-7-F<br>SOT-23<br>M4NEX90BT |  | DDZXS6AQ-7<br>SOT-23<br>G02SV6UBAT |  | DDZXS6AQ-7<br>SOT-23<br>N4056F-QE10742107 |  | MMBD4448HCWQ-7-F<br>SOT-353<br>S00030BHJ |  | DHVS030045SQ-7<br>SOD-123<br>B1031BMF-JK |  | DHVS030045SQ-7<br>SOT-23<br>B1031BMF-JK |  |
|  |  | Wafer            |  | Die Size (W/L/Thickness) - After Saw                |  |                          |  | 0.35*0.35mm*225+/-10um                           |  | 0.35*0.35mm*220+/-20um                |  | 0.35*0.35*0.20mm                     |  | 0.35*0.35*0.20mm                   |  | 0.35*0.35*0.22mm                          |  | 0.35*0.35*0.23mm                         |  | 0.4*0.4*0.2(mm)                          |  | 0.4*0.4*0.2(mm)                         |  |
|  |  | Wafer            |  | Die Process / Technology                            |  |                          |  | Zener diode                                      |  | Zener diode                           |  | Zener diode                          |  | Zener diode                        |  | Zener diode                               |  | switching diode                          |  | switching diode                          |  | switching diode                         |  |
|  |  | Wafer            |  | Wafer FAB Site/Location                             |  |                          |  | JK Liteon/Xinzh                                  |  | SFAB/SH                               |  | Phenittec 1st Fab/Japan              |  | Phenittec 1st Fab/Japan            |  | JK Liteon/Xinzh                           |  | Okayama/Phenittec                        |  | LSC JK Fab                               |  | LSC JK Fab                              |  |
|  |  | Wafer            |  | Wafer Diameter                                      |  |                          |  | 6"                                               |  | 6"                                    |  | 6"                                   |  | 6"                                 |  | 6"                                        |  | 5"                                       |  | 6 inch                                   |  | 6 inch                                  |  |
|  |  | Wafer            |  | No of masks Steps                                   |  |                          |  | 4                                                |  | NA                                    |  | 5                                    |  | 4                                  |  | NA                                        |  | 4                                        |  | 5                                        |  | 5                                       |  |
|  |  | Wafer            |  | Front Metal Type                                    |  |                          |  | AlSiCu                                           |  | NA                                    |  | TiAl-AlSiCu                          |  | TiAl-AlSiCu                        |  | TiAlu                                     |  | AlSiCu                                   |  | AlSiCu                                   |  | AlSiCu                                  |  |
|  |  | Wafer            |  | Front Metal Layer Number/Thickness                  |  |                          |  | 2um                                              |  | NA                                    |  | TiAl(0.13um/0.37um)-AlSiCu(3.0um)    |  | 3.5um                              |  | 500A/5000A                                |  | 2.5um                                    |  | 3.5um                                    |  | 3.5um                                   |  |
|  |  | Wafer            |  | Front Solderable or Plated Metal Type / Thickness   |  |                          |  | NA                                               |  | NA                                    |  | NA                                   |  | NA                                 |  | 4                                         |  | 6                                        |  | N/A                                      |  | N/A                                     |  |
|  |  | Wafer            |  | Back Metal Type (All Layers)                        |  |                          |  | TiAu                                             |  | Ni/V/Au                               |  | Au                                   |  | Au-As-Au                           |  | Au-As-Au                                  |  | AuAs-Au                                  |  | TiAu                                     |  | TiAu                                    |  |
|  |  | Wafer            |  | Back Metal Thickness (All Layers)                   |  |                          |  | 5000A                                            |  | NA                                    |  | 0.9um                                |  | PdCu                               |  | 0.9um                                     |  | PdCu                                     |  | 500/5000A                                |  | 500/5000A                               |  |
|  |  | Wafer            |  | Die Conformal Coating (Passivation) Material        |  |                          |  | NA                                               |  | NA                                    |  | NSG                                  |  | NSG                                |  | SiO2                                      |  | SIN                                      |  | none                                     |  | none                                    |  |
|  |  | Wafer            |  | Die Conformal Coating (Passivation) Thickness Range |  |                          |  | 16500A~18500A                                    |  | NA                                    |  | 3000A                                |  | 3000A                              |  | 6,000A-9,000A                             |  | 8000A                                    |  | N/A                                      |  | N/A                                     |  |
|  |  | Assembly         |  | Die quantity per package (e.g. single or dual dies) |  |                          |  | single                                           |  | single                                |  | single                               |  | single                             |  | dual                                      |  | 4                                        |  | Single                                   |  | 2                                       |  |
|  |  | Assembly         |  | Die Attach Method (DB Epoxy/Solder Type)            |  |                          |  | Eutectic                                         |  | Eutectic                              |  | Eutectic                             |  | Eutectic                           |  | Eutectic                                  |  | Eutectic                                 |  | Eutectic                                 |  | Eutectic                                |  |
|  |  | Assembly         |  | Die Attach Material/Supplier                        |  |                          |  | n/a                                              |  | n/a                                   |  | n/a                                  |  | n/a                                |  | n/a                                       |  | n/a                                      |  | N/A                                      |  | N/A                                     |  |
|  |  | Assembly         |  | Bond Wire/Clip Bond Material                        |  |                          |  | PdCu                                             |  | PdCu                                  |  | PdCu                                 |  | PdCu                               |  | PdCu                                      |  | PdCu                                     |  | PdCu                                     |  | PdCu                                    |  |
|  |  | Assembly         |  | Bond Wire Diameter                                  |  |                          |  | 1.0mil                                           |  | 1.0mil                                |  | 1.0mil                               |  | 1.0mil                             |  | 1.0mil                                    |  | 1.0mil                                   |  | 1.0mil                                   |  | 1.0mil                                  |  |
|  |  | Assembly         |  | Bond Type (at Die)                                  |  |                          |  | Thermo Sonic                                     |  | Thermo Sonic                          |  | Thermo Sonic                         |  | Thermo Sonic                       |  | Thermo Sonic                              |  | Thermo Sonic                             |  | Thermo-Ultrasonic                        |  | Thermo-Ultrasonic                       |  |
|  |  | Assembly         |  | Bond Type (at LF)                                   |  |                          |  | Thermo Sonic                                     |  | Thermo Sonic                          |  | Thermo Sonic                         |  | Thermo Sonic                       |  | Thermo Sonic                              |  | Thermo Sonic                             |  | Thermo-Ultrasonic                        |  | Thermo-Ultrasonic                       |  |
|  |  | Assembly         |  | No. of bond over active area                        |  |                          |  | 1                                                |  | 1                                     |  | 2                                    |  | 2                                  |  | 2                                         |  | 4                                        |  | 1                                        |  | 2                                       |  |
|  |  | Assembly         |  | Leadframe Type                                      |  |                          |  | SOD-123B                                         |  | SOD-123B                              |  | SOT-23C                              |  | SOT-23C                            |  | SOT-23C                                   |  | SOT-353 E                                |  | SOD123B                                  |  | SOT-23C27R                              |  |
|  |  | Assembly         |  | Leadframe Material                                  |  |                          |  | Alloy42                                          |  | Alloy42                               |  | Alloy42                              |  | Alloy42                            |  | Alloy42                                   |  | Alloy42                                  |  | Alloy42                                  |  | Alloy42                                 |  |
|  |  | Assembly         |  | Die Pad Plating Material                            |  |                          |  | Copper plating                                   |  | Copper plating                        |  | Copper plating                       |  | Copper plating                     |  | Copper plating                            |  | Copper plating                           |  | Copper plating                           |  | Copper plating                          |  |
|  |  | Assembly         |  | Mold Compound Type                                  |  |                          |  | CEL-1700HF40SK-D3                                |  | CEL-1700HF40SK-D3                     |  | CEL-1700HF40SK-D3                    |  | CEL-1700HF40SK-D3                  |  | CEL-1700HF40SK-D3                         |  | CEL-1700HF40SK-D3                        |  | CEL-1700HF40SK-D3                        |  | CEL-1700HF40SK-D3                       |  |
|  |  | Assembly         |  | Glass Transition Temp (Tg)                          |  |                          |  | 150°C                                            |  | 125°C                                 |  | 125°C                                |  | 165°C                              |  | 125°C                                     |  | 165°C                                    |  | 150°C                                    |  | 150°C                                   |  |
|  |  | Assembly         |  | Green Compound (Yes/No)                             |  |                          |  | Yes                                              |  | Yes                                   |  | Yes                                  |  | Yes                                |  | Yes                                       |  | n/a                                      |  | Yes                                      |  | Yes                                     |  |
|  |  |                  |  |                                                     |  |                          |  |                                                  |  |                                       |  |                                      |  |                                    |  |                                           |  |                                          |  |                                          |  |                                         |  |